



Torex...Powerfully Small!

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6190xxxx8R-G
Typical Mass: 1.3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.154	Silicon	118300	7440-21-3
		- Arsenic	<1	7440-38-2
Lead pad	0.177	Nickel	135900	7440-02-0
	0.003	Gold	2500	7440-57-5
Die attach	0.022	Epoxy Resin	16700	—
	0.013	Acrylic Resin	10000	—
Bonding wire	0.045	Gold	34900	7440-57-5
Resin	0.587	Silica	451300	60676-86-0
	0.083	Epoxy Resin	64100	—
	0.083	Phenol Resin	64100	—
	0.114	Metal hydroxide	87600	—
	0.019	Silica (crystal)	14600	14808-60-7

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."